

WORLDWIDE ELECTRONIC MATERIALS MARKET ANALYSIS AND FORECASTS**Table of Contents**

| | | |
|------------------|------------------------------------|------------|
| Chapter 1 | Introduction | 1-1 |
| Chapter 2 | Executive Summary | 2-1 |
| 2.1 | Key Industry Trends | 2-1 |
| 2.2 | Market Outlook | 2-4 |
| 2.3 | Supplier Opportunities | 2-6 |
| Chapter 3 | IC Industry Trends | 3-1 |
| 3.1 | IC Industry Growth Forecast | 3-1 |
| 3.2 | Trends in IC Processing Technology | 3-4 |
| Chapter 4 | Liquid Chemicals | 4-1 |
| 4.1 | Technology Issues | 4-1 |
| 4.1.1 | Acids and Solvents | 4-1 |
| 4.1.2 | Resists | 4-5 |
| 4.2 | Purity Requirements | 4-14 |
| 4.2.1 | Purification Methods | 4-14 |
| o | Trends For Purity - Trace Elements | 4-15 |
| 4.2.2 | Particulates | 4-16 |
| o | Effects on Yield | 4-16 |
| o | Particulate Removal Techniques | 4-22 |
| o | Particle Monitoring | 4-23 |
| 4.3 | Chemical Management | 4-24 |

| | | |
|------------------|---|------------|
| 4.3.1 | Introduction | 4-24 |
| 4.3.2 | Chemical Usage Reduction | 4-26 |
| | | |
| Chapter 5 | Gases | 5-1 |
| | | |
| 5.1 | Technology Issues | 5-1 |
| 5.2 | Requirements | 5-3 |
| 5.2.1 | Purification Alternatives | 5-3 |
| o | Historical Perspective | 5-3 |
| o | Trends For Purity - Consistency | 5-5 |
| 5.2.2 | Particulate Considerations | 5-7 |
| o | Particle Monitoring | 5-7 |
| o | Filtration Methods | 5-9 |
| 5.2.3 | Summary | 5-13 |
| | | |
| Chapter 6 | Sputtering and Evaporation Materials | 6-1 |
| | | |
| 6.1 | Technology Issues | 6-1 |
| 6.2 | Purity Requirements | 6-10 |
| | | |
| Chapter 7 | Market Forecast | 7-1 |
| | | |
| 7.1 | Market Driving Forces & Assumptions | 7-1 |
| 7.2 | Chemicals and Materials Forecast | 7-6 |
| 7.2.1 | Forecast By Chemical and Material | 7-6 |
| 7.2.2 | Chemical Use Per Unit Area Of Silicon Processed | 7-25 |
| 7.2.3 | Market Shares | 7-27 |
| | | |
| Chapter 8 | Strategic Customer Issues | 8-1 |
| | | |

| | | |
|------------------------|---|------|
| 8.1 | Benchmarking a Vendor | 8-1 |
| 8.1.1 | Statistical Quality Control | 8-1 |
| o | Assay and Related Items | 8-3 |
| o | Trace Elements | 8-4 |
| o | Particles | 8-5 |
| 8.1.2 | Analytical Capabilities | 8-6 |
| 8.1.3 | Product Manufacturing And/Or Sourcing | 8-8 |
| 8.1.4 | General Considerations | 8-9 |
| o | Installation and Retrofitting Costs | 8-9 |
| 8.2 | In-House Quality Control And Assurance | 8-13 |
| 8.2.1 | Analytical Tools | 8-13 |
| 8.2.2 | How Much Testing | 8-15 |
| 8.2.3 | Exhaust Gas Analysis | 8-16 |
| | | |
| List of Figures | | |
| | | |
| 4.1 | Relationship Between Device Yield and Particles | 4-18 |
| 4.2 | Relationship Between Die Yield and Chip Size | 4-20 |
| 4.3 | Chemical Management Services Tasks | 4-25 |
| 6.1 | ITRS Roadmap | 6-3 |
| 6.2 | Gate-Last Approach | 6-8 |
| 6.3 | Gate-First Approach | 6-9 |
| 7.1 | Segmentation of Stepper/Scan Shipments | 7-13 |
| 7.2 | Worldwide Resist Market | 7-15 |
| 7.3 | Lithography Extensions | 7-16 |
| 7.4 | 2014 Silicon Wafer Market | 7-21 |
| 7.5 | 2020 Silicon Wafer Market | 7-22 |
| 7.6 | Cost of Chemicals Per Square Inch of Silicon | 7-26 |
| 7.7 | Worldwide Market Shares for Gas Suppliers | 7-28 |
| 7.8 | Worldwide Market Shares for Liquid Chemical Suppliers | 7-29 |
| 7.9 | Worldwide Market Shares for Photoresist Suppliers | 7-30 |
| 7.10 | Worldwide Market Shares for Silicon Wafer Companies | 7-31 |
| 7.11 | Worldwide Market Shares for Sputtering Target Suppliers | 7-32 |

| | | |
|-----------------------|--|------|
| 7.12 | Pricing Trend For Silicon Wafers | 7-34 |
| | | |
| List of Tables | | |
| | | |
| 4.1 | Common Wafer Processing Chemicals | 4-2 |
| 4.2 | Photoresist Stripping Solutions | 4-10 |
| 5.1 | Gas Control System Issues | 5-2 |
| 5.2 | Potential Hazards of Processing Gases | 5-8 |
| 7.1 | Worldwide Forecast of Chemicals and Materials for IC Manufacturing | 7-8 |
| 7.2 | Worldwide Market Forecast of Si Wafers | 7-19 |
| 7.3 | Worldwide Market Forecast of Sputtering Targets | 7-24 |